



#### 60V 175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI3333-8

### **Product Summary**

BV <sub>DSS</sub>	R <sub>DS(ON)</sub> Max	I <sub>D</sub> Max T <sub>C</sub> = +25°C
	50mΩ @ V <sub>GS</sub> = 10V	18A
60V	63mΩ @ V <sub>GS</sub> = 4.5V	15A

### **Features and Benefits**

- Rated to +175°C—Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Low RDS(ON)—Ensures Minimal On-State Losses
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of the Board Area Occupied by SO-8 Enabling Smaller End Product
- Wettable Flank for Improved Optical Inspections
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at

https://www.diodes.com/products/automotive/automotive-products/.

 This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability.

https://www.diodes.com/quality/product-definitions/

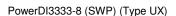
### **Description and Applications**

This MOSFET has been designed to minimize the on-state resistance (RDS(ON)) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

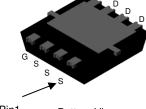
- Power-Management Functions
- DC-DC Converters

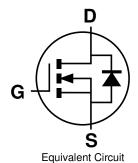
#### **Mechanical Data**

- Case: PowerDI<sup>®</sup>3333-8
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See Diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 **(£3)**
- Weight: 0.072 grams (Approximate)









Top View

Pin1 Bottom View

**Ordering Information** (Note 4)

Part Number	Case	Packaging
DMNH6069SFVW-7	PowerDI3333-8 (SWP) (Type UX)	2,000/Tape & Reel
DMNH6069SFVW-13	PowerDI3333-8 (SWP) (Type UX)	3,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

PowerDI is a registered trademark of Diodes Incorporated.



## **Marking Information**



 $\underline{\text{M69}} = \text{Product Type Marking Code}$  $\underline{\text{YY}}\text{WW} = \text{Date Code Marking}$ YY = Last Two Digits of Year (ex: 21 = 2021) WW = Week Code (01 to 53)

# **Maximum Ratings** (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	$V_{DSS}$	60	V		
Gate-Source Voltage	Vgss	±20	V		
Continuous Drain Current V <sub>GS</sub> = 10V (Note 5)	Steady State	T <sub>A</sub> = +25°C T <sub>A</sub> = +100°C	I <sub>D</sub>	5.0 3.5	А
Continuous Drain Current VGS = 10V (Note 6)	Steady State	$T_{C} = +25^{\circ}C$ $T_{C} = +100^{\circ}C$	l <sub>D</sub>	18 12	А
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%	I <sub>DM</sub>	72	Α		
Maximum Continuous Body Diode Forward Current	ls	5.0	Α		
Pulsed Source Current (380µs Pulse, Duty Cycle = 1	lsм	72	Α		
Avalanche Current , L = 0.1mH			las	12	Α
Repetitive Avalanche Energy , L = 0.1mH			Eas	7.2	mJ

## Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	PD	3.0	W	
Thermal Resistance, Junction to Ambient (Note 5)  Steady State		Rөja	50	°C/W
Total Power Dissipation (Note 6)	P <sub>D</sub>	38	W	
Thermal Resistance, Junction to Case (Note 6)  Steady State		Rejc	3.9	°C/W
Operating and Storage Temperature Range	TJ, TSTG	-55 to +175	°C	

Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.
 Thermal resistance from junction to soldering point (on the exposed drain pad).

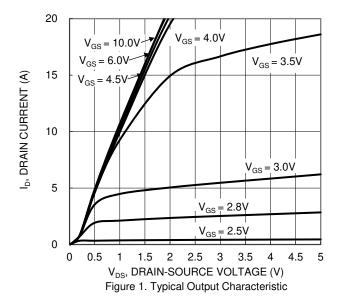


# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	60	_		٧	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current	IDSS	_	_	1	μΑ	$V_{DS} = 60V$ , $V_{GS} = 0V$	
Gate-Source Leakage	Igss	_	_	±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1	_	3	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	R <sub>DS(ON)</sub>		35	50	mΩ	$V_{GS} = 10V$ , $I_D = 3A$	
Static Brain Source on resistance	TIDS(ON)	_	41	63		$V_{GS} = 4.5V, I_D = 2.4A$	
Diode Forward Voltage	VsD	_	0.8	1.1	٧	$V_{GS} = 0V$ , $I_{S} = 2.5A$	
DYNAMIC CHARACTERISTICS (Note 8)							
Input Capacitance	Ciss	_	740	_	pF	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
Output Capacitance	Coss	_	40	_	рF	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V, f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	28	_	pF	11 = 1.UIVIM2	
Gate Resistance	$R_g$	_	2.2	_	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (VGS = 4.5V)	Qg	_	6.4	_	nC		
Total Gate Charge (VGS = 10V)	Qg	_	14	_	nC	V <sub>DS</sub> = 30V, I <sub>D</sub> = 12A	
Gate-Source Charge	Qgs	_	2.8	_	nC	VDS = 30V, ID = 12A	
Gate-Drain Charge	$Q_{gd}$	_	2.3	_	nC	1	
Turn-On Delay Time	t <sub>D(ON)</sub>	_	3.6	_	ns		
Turn-On Rise Time	t <sub>R</sub>	_	5.0	_	ns	$V_{DS} = 30V, I_D = 12A$ $V_{GS} = 10V, R_G = 6.0\Omega$	
Turn-Off Delay Time	tD(OFF)	_	12	_	ns		
Turn-Off Fall Time	tF	_	3.3	_	ns		
Body Diode Reverse Recovery Time	trr	_	11		ns	I <sub>F</sub> = 4.5A, di/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Qrr		5.1	_	nC	1F - 4.5A, αι/αι = 100A/μS	

<sup>7.</sup> Short duration pulse test used to minimize self-heating effect. 8. Guaranteed by design. Not subject to product testing.





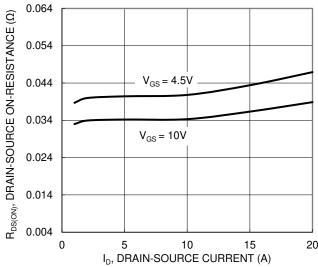


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

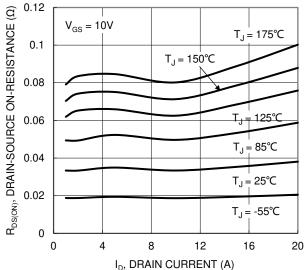


Figure 5. Typical On-Resistance vs. Drain Current and Temperature

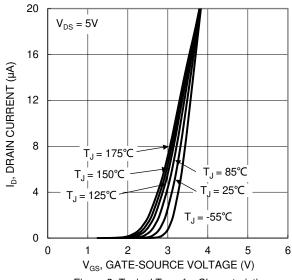


Figure 2. Typical Transfer Characteristic

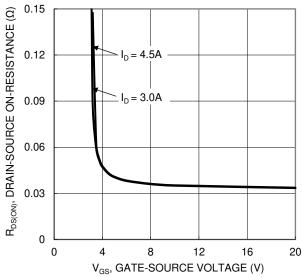


Figure 4. Typical Transfer Characteristic

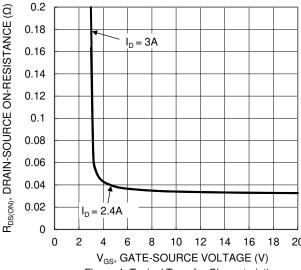


Figure 4. Typical Transfer Characteristic



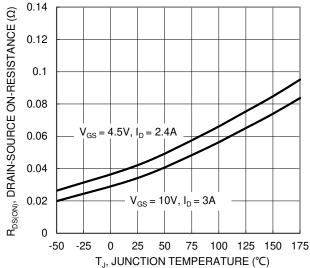


Figure 7. On-Resistance Variation with Temperature

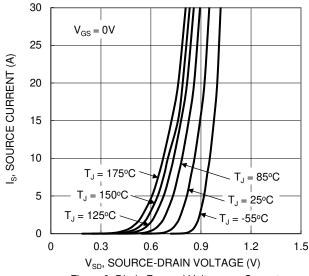
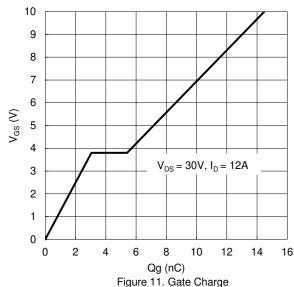


Figure 9. Diode Forward Voltage vs. Current



3  $V_{GS(TH)}, \ GATE\ THRESHOLD\ VOLTAGE\ (V)$ 2.5 2  $I_D = 1mA$ 1.5  $I_D = 250 \mu A$ 1 0.5 0 -25 25 50 100 125 150 175 -50 75 T<sub>J</sub>, JUNCTION TEMPERATURE (°C)

Figure 8. Gate Threshold Variation vs. Temperature

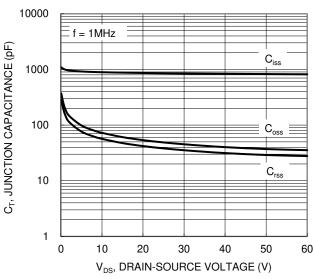


Figure 10. Typical Junction Capacitance

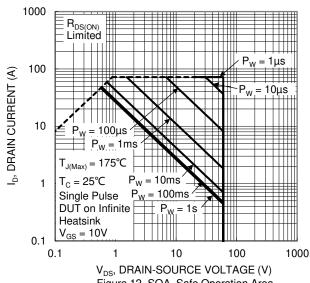


Figure 12. SOA, Safe Operation Area



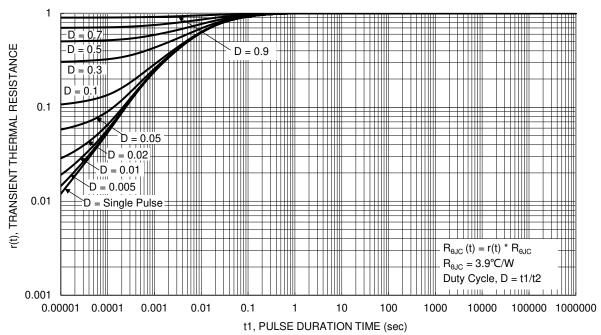


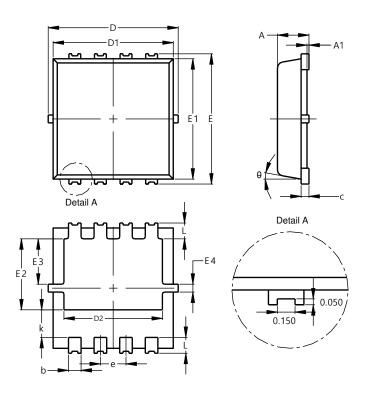
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)

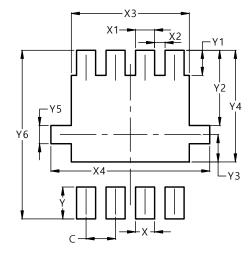


PowerDI3333-8 (SWP)						
(Type UX)						
Dim	Min Max		Тур			
Α	0.75	0.85	0.80			
A1	0.00	0.05	_			
b	0.25	0.40	0.32			
С	0.10	0.25	0.15			
D	3.20	3.40	3.30			
D1	2.95	3.15	3.05			
D2	2.30	2.70	2.50			
E	3.20	3.40	3.30			
E1	2.95	3.15	3.05			
E2	1.60	2.00	1.80			
E3	0.95	1.35	1.15			
E4	0.10	0.30	0.20			
е	_	_	0.65			
k	0.50	0.90	0.70			
١	0.30	0.50	0.40			
θ	0°	12°	10°			
All Dimensions in mm						

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI3333-8 (SWP) (Type UX)



Dimensions	Value (in mm)			
С	0.650			
X	0.420			
X1	0.420			
X2	0.230			
Х3	2.600			
X4	3.500			
Υ	0.700			
Y1	0.550			
Y2	1.650			
Y3	0.600			
Y4	2.450			
Y5	0.400			
Y6	3.700			



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